

## C1210C189B2TACTU

Aliases (C1210C189B2TAC7800)

SMD Comm X8G HT150C, Ceramic, 1.8 pF, +/-0.1 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	30 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	1210	
L	3.2mm +/-0.2mm	
W	2.5mm +/-0.2mm	
Т	0.78mm +/-0.10mm	
S	1.5mm MIN	
В	0.5mm +/-0.25mm	

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Packaging Specifications	

Specifications	
Capacitance	1.8 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.1 pF
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
Packaging Quantity	4000	Dissipation Factor	0.1% 1 MHz
		Aging Rate	0% Loss/D Time is 100

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